Properly measured destruction or removal efficiency means destruction or removal efficiencies measured in accordance with EPA 430–R–10–003 (incorporated by reference, see §98.7).

The Random Sampling Abatement System Testing Program (RSASTP) means the required frequency for measuring the destruction or removal efficiencies of abatement systems in order to apply properly measured destruction or removal efficiencies to report controlled emissions.

Redundant abatement systems means a system that is specifically designed, installed and operated for the purpose of destroying fluorinated GHGs and N₂O gases. A redundant abatement system is used as a backup to the main fluorinated GHGs and N₂O abatement system during those times when the main system is not functioning or operating in accordance with design and operating specifications.

Repeatable means that the variables used in the formulas for the facility’s engineering model for gas apportioning factors are based on observable and measurable quantities that govern gas consumption rather than engineering judgment about those quantities or gas consumption.

Similar, with respect to recipes, means those recipes that are composed of the same set of chemicals and have the same flow stabilization times and where the documented differences, considered separately, in reactor pressure, individual gas flow rates, and applied radio frequency (RF) power are less than or equal to plus or minus 10 percent. For purposes of comparing and documenting recipes that are similar, facilities may use either the best known method provided by an equipment manufacturer or the process of record, for which emission factors for either have been measured.

Trigger point for change out means the residual weight or pressure of a gas container type that a facility uses to change out that gas container.

Uptime means the ratio of the total time during which the abatement system is in an operational mode with fluorinated GHGs or N₂O flowing through production process tool(s) connected to that abatement system, to the total time during which fluorinated GHGs or N₂O are flowing through production process tool(s) connected to that abatement system.

Wafer cleaning is a process type that consists of any production process using fluorinated GHG reagents to clean wafers at any step during production.

Wafer passes is a count of the number of times a wafer substrate is processed in a specific process recipe, sub-type, or type. The total number of wafer passes over a reporting year is the number of wafer passes per tool multiplied by the number of operational process tools in use during the reporting year.

Wafer starts means the number of fresh wafers that are introduced into the fabrication sequence each month. It includes test wafers, which means wafers that are exposed to all of the conditions of process characterization, including but not limited to actual etch conditions or actual film deposition conditions.

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**Table I–1 to Subpart I—Default Emission Factors for Threshold Applicability Determination**

<table>
<thead>
<tr>
<th>Product type</th>
<th>CF₄</th>
<th>C₂F₆</th>
<th>CHF₃</th>
<th>C₃F₈</th>
<th>NF₃</th>
<th>SF₆</th>
</tr>
</thead>
<tbody>
<tr>
<td>Semiconductors (kg/m²) ........................</td>
<td>0.90</td>
<td>1.00</td>
<td>0.04</td>
<td>0.05</td>
<td>0.04</td>
<td>0.20</td>
</tr>
<tr>
<td>LCD (g/m²) ........................................</td>
<td>0.50</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>0.90</td>
<td>4.00</td>
</tr>
<tr>
<td>MEMS (kg/m²) .....................................</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>NA</td>
<td>1.02</td>
</tr>
</tbody>
</table>

Notes: NA denotes not applicable based on currently available information.